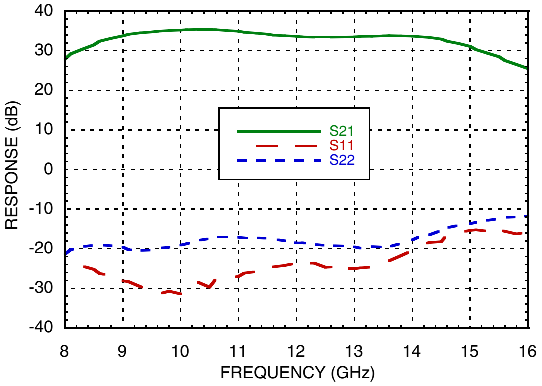
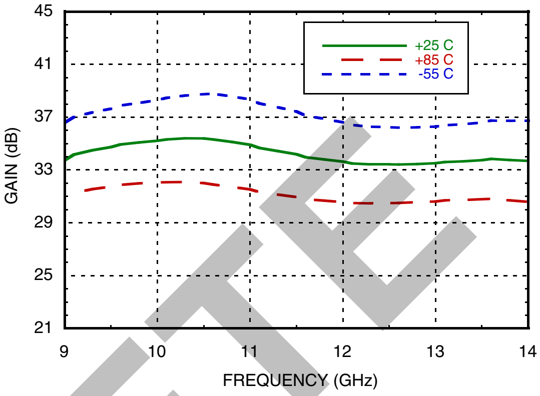
GaAs pHEMT MMIC 5 WATT POWER AMPLIFIER With Power Detector, 9 - 14 GHz

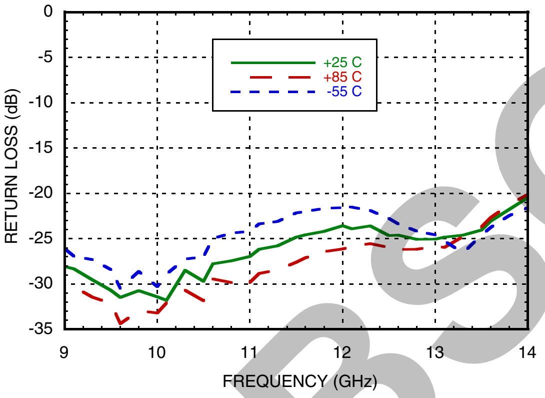
Broadband Gain & Return Loss vs. Frequency



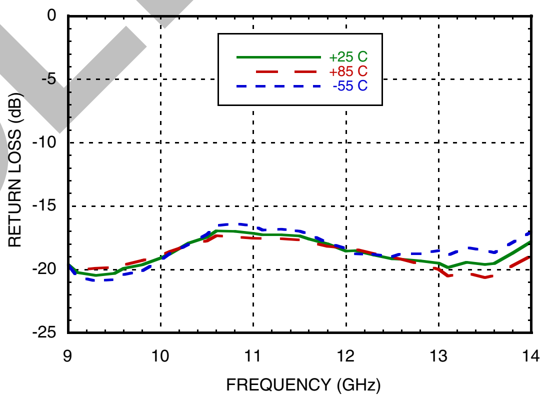
Gain vs. Temperature



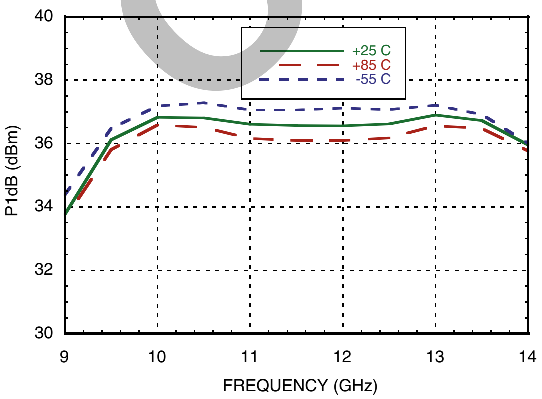
Input Return Loss vs. Temperature



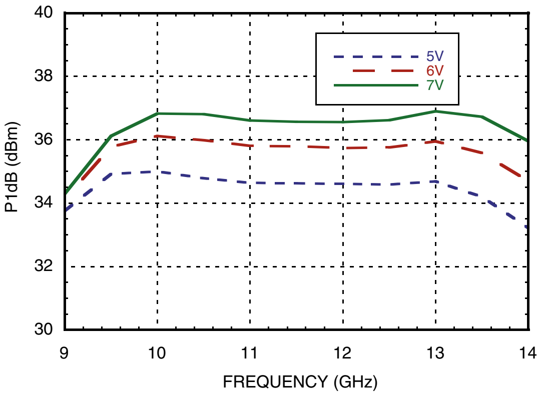
Output Return Loss vs. Temperature



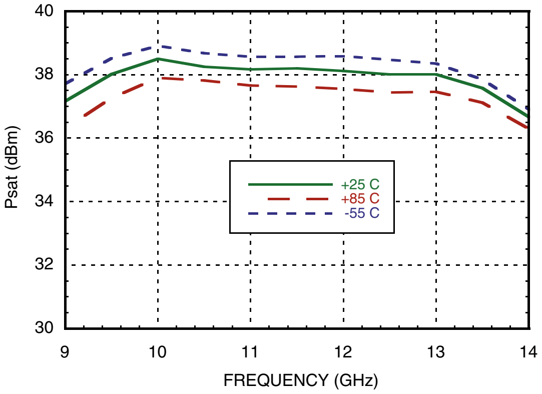
P1dB vs. Temperature



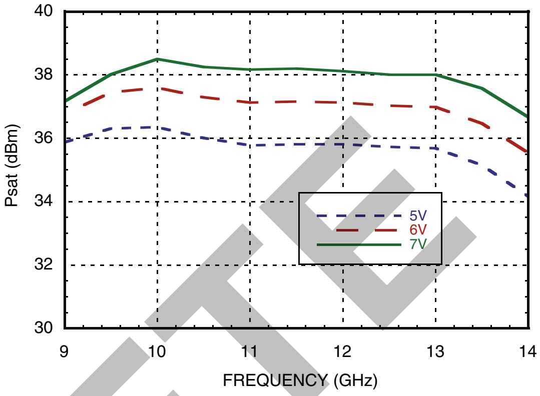
P1dB vs. Supply Voltage



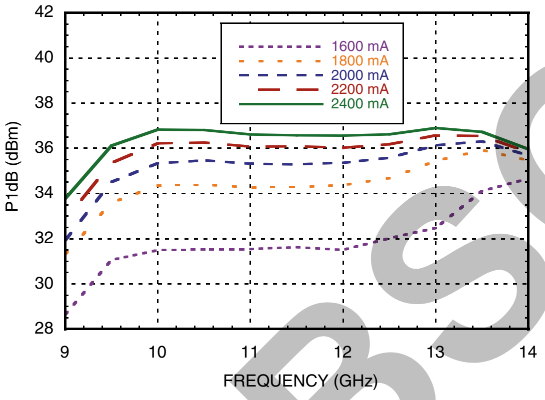
Psat vs. Temperature



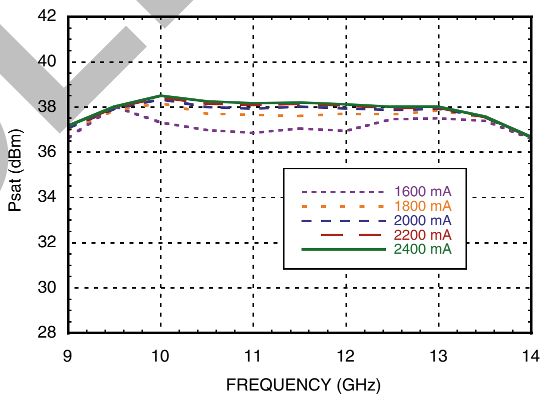
Psat vs. Supply Voltage



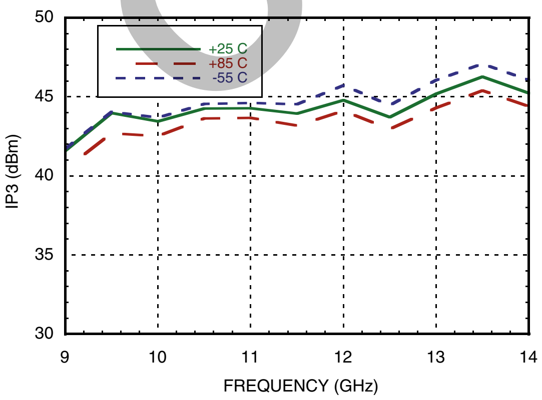
P1dB vs. Supply Current (Idd)



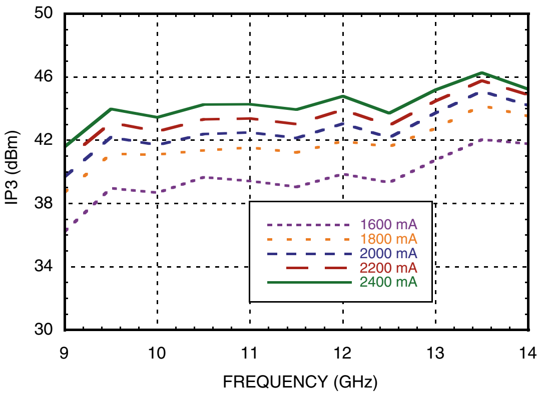
Psat vs. Supply Current (Idd)



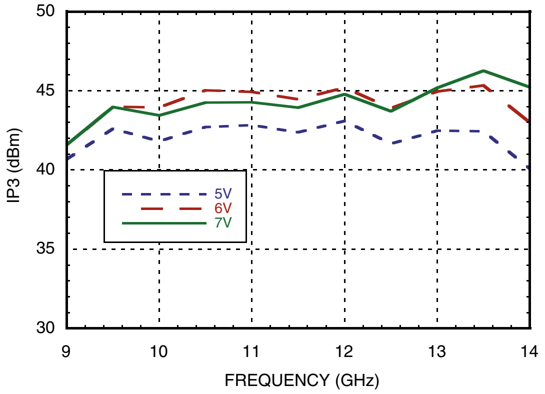
**Output IP3 vs.
Temperature, Pout/Tone = +22 dBm**



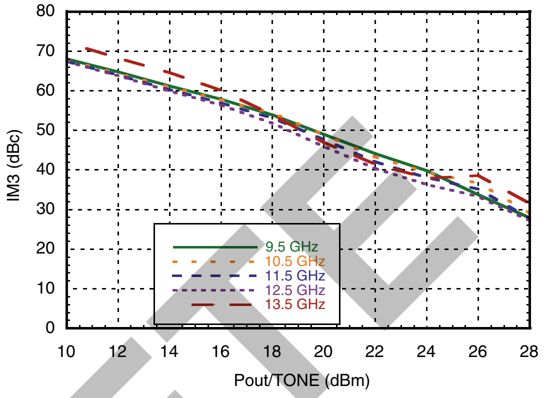
**Output IP3 vs.
Supply Current, Pout/Tone = +22 dBm**



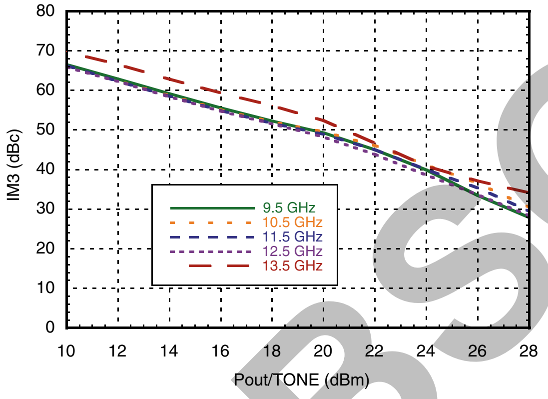
Output IP3 vs. Supply Voltage, Pout/Tone = +22 dBm



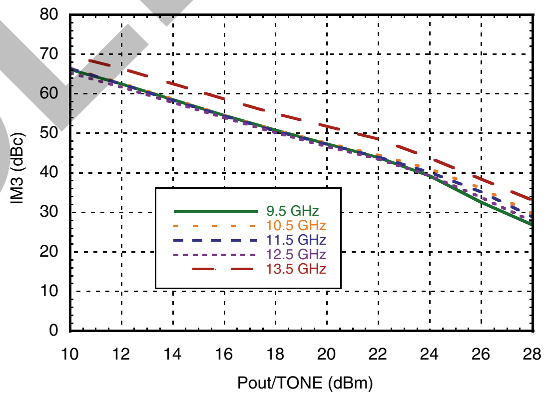
Output IM3 @ Vdd = +5V



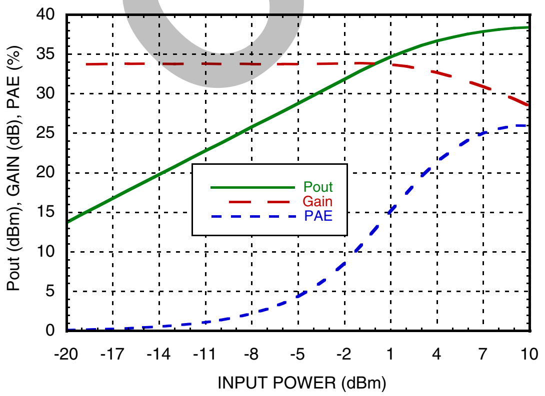
Output IM3 @ Vdd = +6V



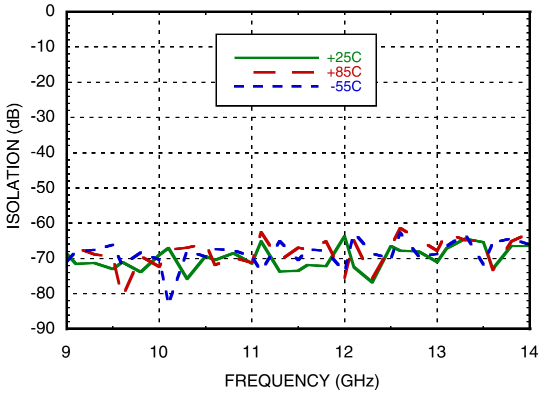
Output IM3 @ Vdd = +7V



Power Compression @ 11.5 GHz

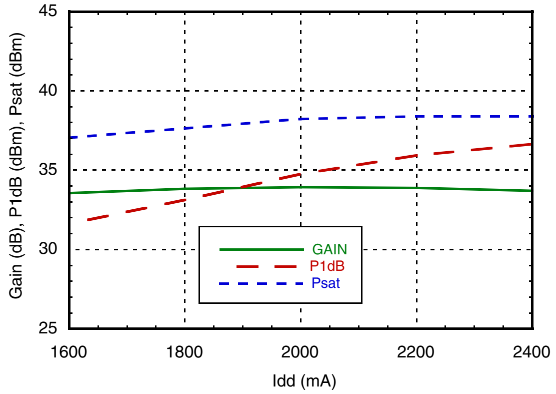


Reverse Isolation vs. Temperature

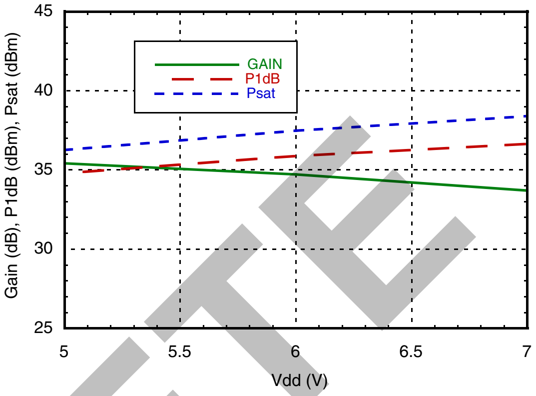


GaAs pHEMT MMIC 5 WATT POWER AMPLIFIER With Power Detector, 9 - 14 GHz

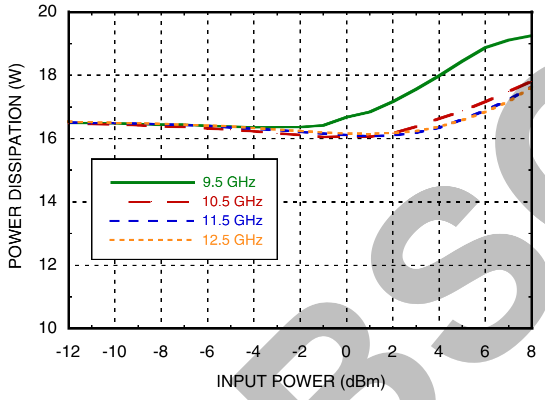
Gain & Power vs. Supply Current @ 11.5 GHz



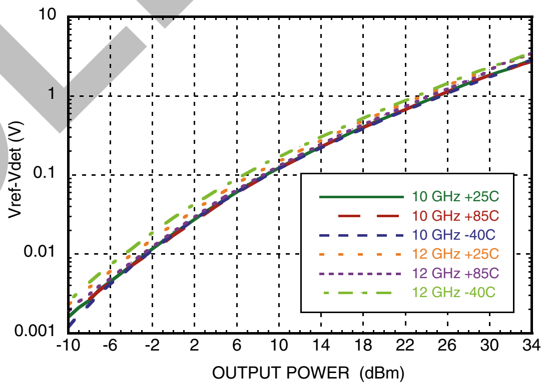
Gain & Power vs. Supply Voltage @ 11.5 GHz



Power Dissipation



Detector Voltage vs. Frequency & Temperature



Absolute Maximum Ratings

Drain Bias Voltage (Vdd)	+8V
RF Input Power (RFIN)	+27 dBm
Channel Temperature	150 °C
Continuous Pdiss (T= 85 °C) (derate 306 mW/°C above 85 °C)	19.9 W
Thermal Resistance (channel to die bottom)	3.27 °C/W
Storage Temperature	-65 to +150 °C
Operating Temperature	-55 to +85 °C

Typical Supply Current vs. Vdd

Vdd (V)	Idd (mA)
+5.0	2400
+6.0	2400
+7.0	2400

Note: Amplifier will operate over full voltage ranges shown above, Vgg1, Vgg2 adjusted to achieve Idd = 2400 mA at +7V

ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS

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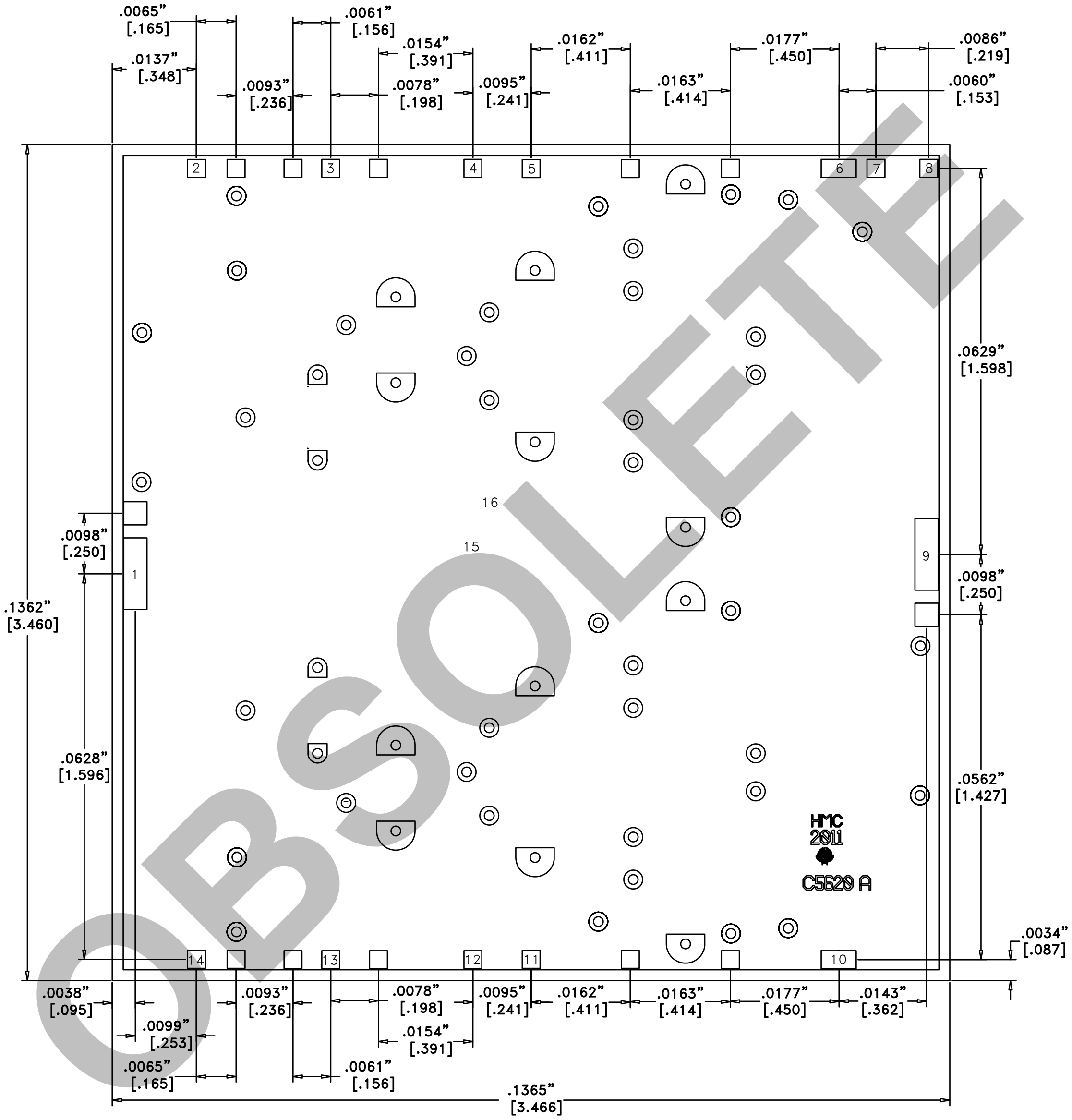
GaAs pHEMT MMIC 5 WATT POWER AMPLIFIER
With Power Detector, 9 - 14 GHz

Outline Drawing



NOTES:
1. ALL DIMENSIONS ARE IN INCHES [MM]
2. DIE THICKNESS IS .004"
3. TYPICAL BOND PAD IS .004" SQUARE
4. BACKSIDE METALLIZATION: GOLD
5. BOND PAD METALLIZATION: GOLD
6. BACKSIDE METAL IS GROUND.
7. CONNECTION NOT REQUIRED FOR UNLABELED BOND PADS.
8. OVERALL DIE SIZE ± .002

Die Packaging Information [1]

Standard	Alternate
GP-1 (Gel Pack)	[2]

[1] Refer to the "Packaging Information" section for die packaging dimensions.
[2] For alternate packaging information contact Hittite Microwave Corporation.

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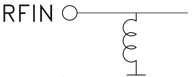
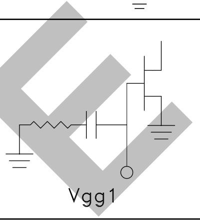
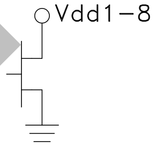
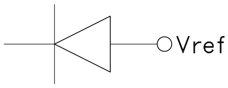
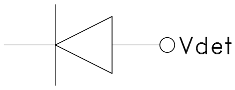
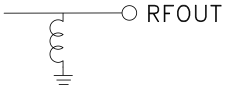
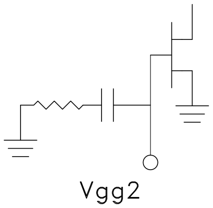
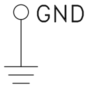
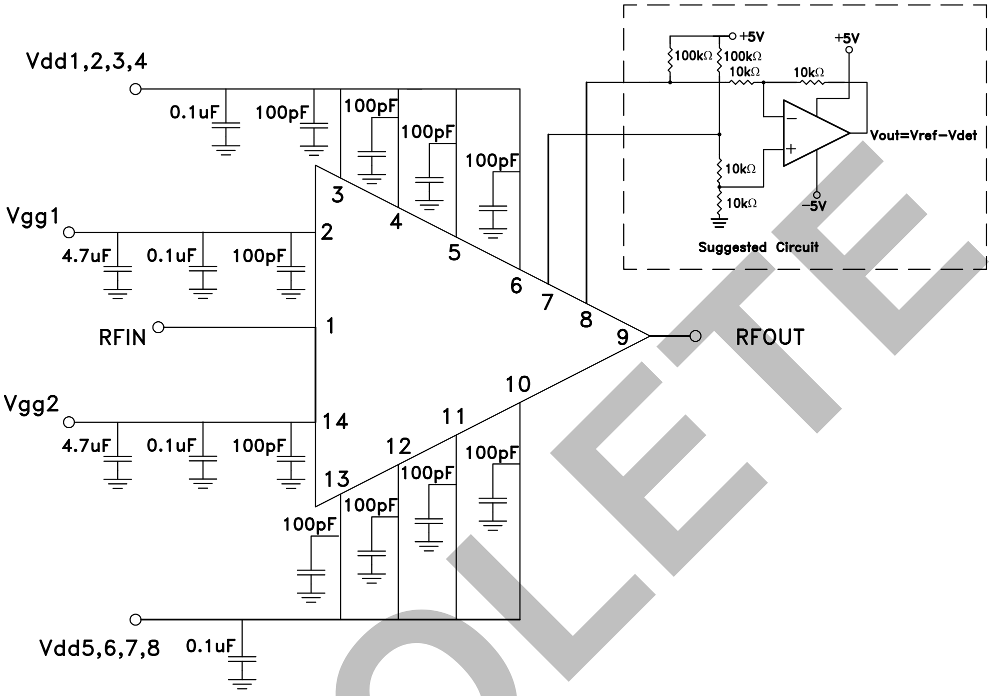
GaAs pHEMT MMIC 5 WATT POWER AMPLIFIER
With Power Detector, 9 - 14 GHz

Pad Descriptions

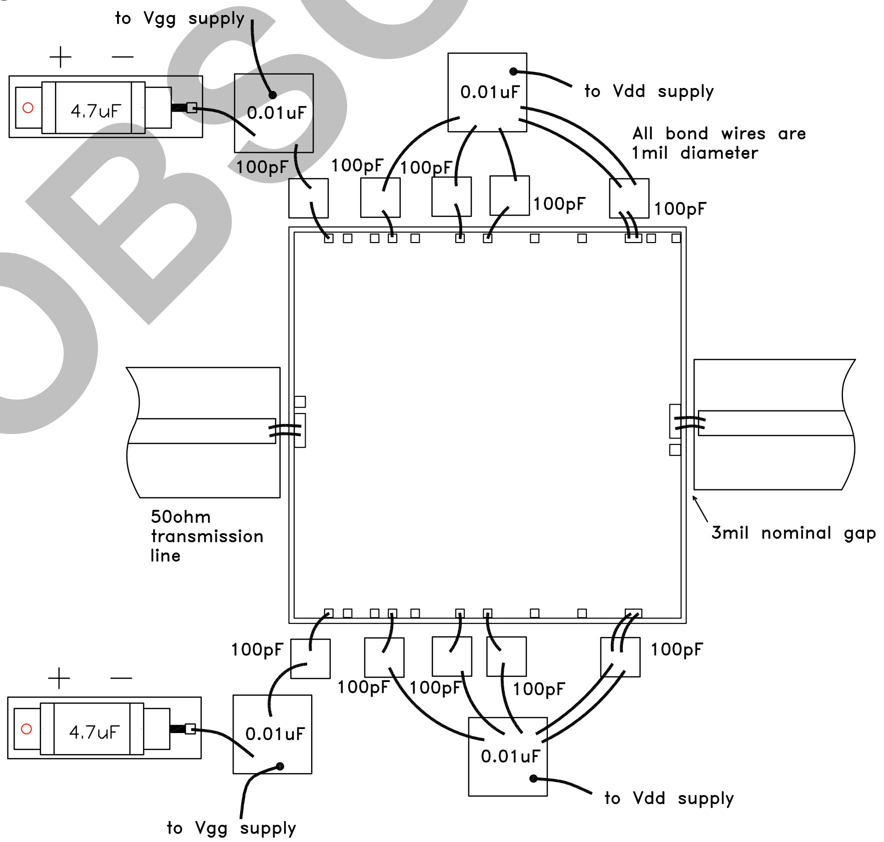
Pad Number	Function	Description	Interface Schematic
1	RFIN	This pad is DC coupled and matched to 50 Ohms over the operating frequency range.	
2	Vgg1	Gate control for amplifier, Vdd1 - Vdd4. External bypass capacitors of 100 pF, 0.01 µF and 4.7 µF are required.	
3 - 6 10 - 13	Vdd1, Vdd2, Vdd3, Vdd4 Vdd5, Vdd6, Vdd7, Vdd8	Drain bias voltage for the amplifier. External bypass capacitors of 100 pF are required for each pad, followed by common 0.1 µF capacitors.	
7	Vref	DC voltage of diode biased through external resistor, used for temperature compensation of Vdet.	
8	Vdet	DC voltage representing RF output power rectified by diode which is biased through an external resistor.	
9	RFOUT	This pad is DC coupled and matched to 50 Ohms.	
14	Vgg2	Gate control for amplifier, Vdd5 - Vdd8. External bypass capacitors of 100 pF, 0.01 µF and 4.7 µF are required.	
Die Bottom	GND	Die bottom must be connected to RF/DC ground.	

GaAs pHEMT MMIC 5 WATT POWER AMPLIFIER With Power Detector, 9 - 14 GHz

Application Circuit



Assembly Diagram



Mounting & Bonding Techniques for Millimeterwave GaAs MMICs

The die should be attached directly to the ground plane eutectically or with conductive epoxy (see HMC general Handling, Mounting, Bonding Note).

50 Ohm Microstrip transmission lines on 0.127mm (5 mil) thick alumina thin film substrates are recommended for bringing RF to and from the chip (Figure 1). If 0.254mm (10 mil) thick alumina thin film substrates must be used, the die should be raised 0.150mm (6 mils) so that the surface of the die is coplanar with the surface of the substrate. One way to accomplish this is to attach the 0.102mm (4 mil) thick die to a 0.150mm (6 mil) thick molybdenum heat spreader (moly-tab) which is then attached to the ground plane (Figure 2).

Microstrip substrates should be located as close to the die as possible in order to minimize bond wire length. Typical die-to-substrate spacing is 0.076mm to 0.152 mm (3 to 6 mils).

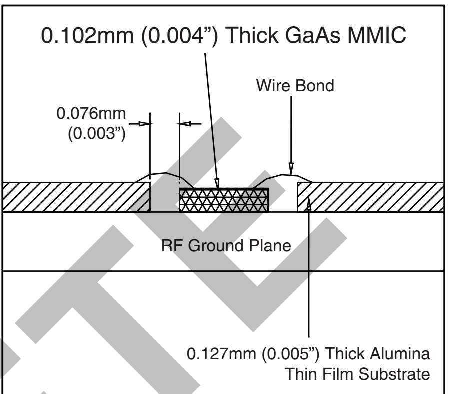


Figure 1.

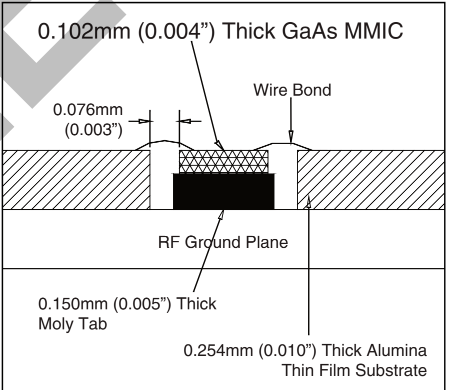


Figure 2.

Handling Precautions

Follow these precautions to avoid permanent damage.

Storage: All bare die are placed in either Waffle or Gel based ESD protective containers, and then sealed in an ESD protective bag for shipment. Once the sealed ESD protective bag has been opened, all die should be stored in a dry nitrogen environment.

Cleanliness: Handle the chips in a clean environment. DO NOT attempt to clean the chip using liquid cleaning systems.

Static Sensitivity: Follow ESD precautions to protect against > ± 250V ESD strikes.

Transients: Suppress instrument and bias supply transients while bias is applied. Use shielded signal and bias cables to minimize inductive pickup.

General Handling: Handle the chip along the edges with a vacuum collet or with a sharp pair of bent tweezers. The surface of the chip may have fragile air bridges and should not be touched with vacuum collet, tweezers, or fingers.

Mounting

The chip is back-metallized and can be die mounted with AuSn eutectic preforms or with electrically conductive epoxy. The mounting surface should be clean and flat.

Eutectic Die Attach: A 80/20 gold tin preform is recommended with a work surface temperature of 255 °C and a tool temperature of 265 °C. When hot 90/10 nitrogen/hydrogen gas is applied, tool tip temperature should be 290 °C. DO NOT expose the chip to a temperature greater than 320 °C for more than 20 seconds. No more than 3 seconds of scrubbing should be required for attachment.

Epoxy Die Attach: Apply a minimum amount of epoxy to the mounting surface so that a thin epoxy fillet is observed around the perimeter of the chip once it is placed into position. Cure epoxy per the manufacturer’s schedule.

Wire Bonding

Ball or wedge bond with 0.025mm (1 mil) diameter pure gold wire. Thermosonic wirebonding with a nominal stage temperature of 150 °C and a ball bonding force of 40 to 50 grams or wedge bonding force of 18 to 22 grams is recommended. Use the minimum level of ultrasonic energy to achieve reliable wirebonds. Wirebonds should be started on the chip and terminated on the package or substrate. All bonds should be as short as possible <0.31mm (12 mils).

Notes: